

#### **Description**

ACE4010M uses advanced trench technology to provide excellent R<sub>DS(ON)</sub>.

This device particularly suits for low voltage application such as power management of desktop computer or notebook computer power management, DC/DC converter.

#### **Features**

- Low r<sub>DS(on)</sub> trench technology
- Low thermal impedance
- Fast switching speed

#### **Applications:**

- PoE Power Sourcing Equipment
- PoE Powered Devices
- Telecom DC/DC converters
- White LED boost converters

#### **Absolute Maximum Ratings**

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		$V_{DS}$	100	V
Gate-Source Voltage		$V_{GS}$	±20	V
Continuous Drain Current	T <sub>C</sub> =25°C	I <sub>D</sub>	26	۸
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	50	А
Continuous Source Current (Diode Conduction)		Is	50	Α
Power Dissipation	T <sub>C</sub> =25°C	$P_D$	50	W
Operating Junction and Storage Temperature Range		$T_J, T_stg$	-55 to 175	°C

#### THERMAL RESISTANCE RATINGS

Parameter		Maximum	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	$R_{\theta JA}$	40	°C/W	
Maximum Junction-to-Case	$R_{ heta JC}$	3		

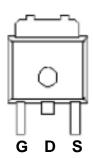
#### Notes

- a. Surface Mounted on 1" x 1" FR4 Board, drain pad using 2 oz copper, value dependent on PC board thermal characteristics.
- b. Pulse width limited by maximum junction temperature.

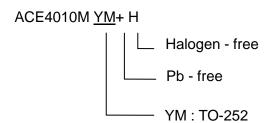


## **Packaging Type**

TO-252



# Ordering information





### **Electrical Characteristics**

T<sub>A</sub>=25°C, unless otherwise specified.

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
		Static					
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \text{ uA}$	1		3.5	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = 20 \text{ V}$			±100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}$			1		
	I <sub>DSS</sub>	$V_{DS} = 80V, V_{GS} = 0 V, T_{J} = 55^{\circ}C$			25	uA	
On-State Drain Current	I <sub>D(on)</sub>	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	34			Α	
Drain-Source On-Resistance		$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$			36	m O	
	r <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 9.2 \text{ A}$			42	mΩ	
Forward Transconductance	g <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_{D} = 10 \text{ A}$		10		S	
Diode Forward Voltage	V <sub>SD</sub>	$I_S = 25 \text{ A}, V_{GS} = 0 \text{ V}$		0.89		V	
		Dynamic					
Total Gate Charge	Qg	$V_{DS} = 50 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		14.8		nC	
Gate-Source Charge	$Q_{gs}$			4.3			
Gate-Drain Charge	$Q_{gd}$			8.6			
Turn-On Delay Time	t <sub>d(on)</sub>			4.8			
Rise Time	t <sub>r</sub>	$V_{DD}$ = 50 V, $R_L$ = 5 $\Omega$ , $I_D$ = 10 A, $V_{GEN}$ = 10 V, $R_{GEN}$ = 6 $\Omega$		14.2		nS	
Turn-Off Delay Time	t <sub>d(off)</sub>			39.2			
Fall Time	t <sub>f</sub>			25.6			
Input Capacitance	C <sub>iss</sub>			1216		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		154			
ReverseTransfer Capacitance	C <sub>rss</sub>			131			

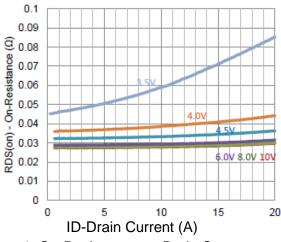
#### Note:

a. Pulse test: PW <= 300us duty cycle <= 2%.

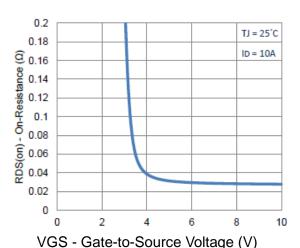
b. Guaranteed by design, not subject to production testing.



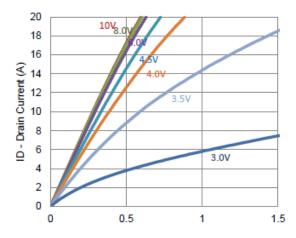
## **Typical Performance Characteristics (N-Channel)**



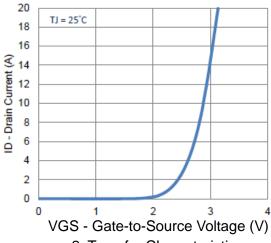
1. On-Resistance vs. Drain Current



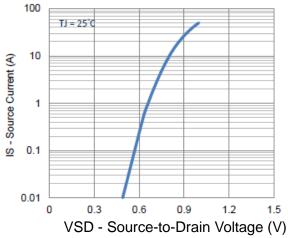
3. On-Resistance vs. Gate-to-Source Voltage



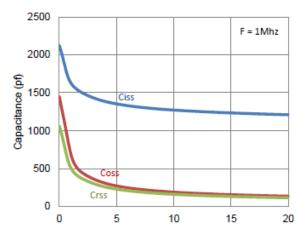
VDS - Drain-to-Source Voltage (V) 5. Output Characteristics



2. Transfer Characteristics



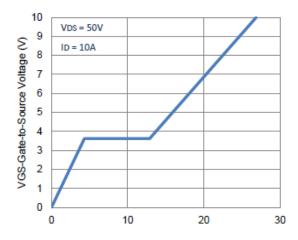
4. Drain-to-Source Forward Voltage



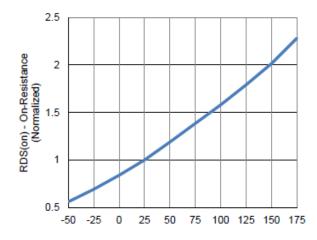
VDS-Drain-to-Source Voltage (V) 6. Capacitance



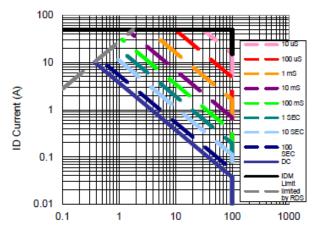
## **Typical Performance Characteristics**



Qg - Total Gate Charge (nC) 7. Gate Charge

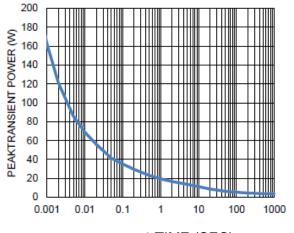


TJ –Junction Temperature(°C)
8. Normalized On-Resistance Vs
Junction Temperature



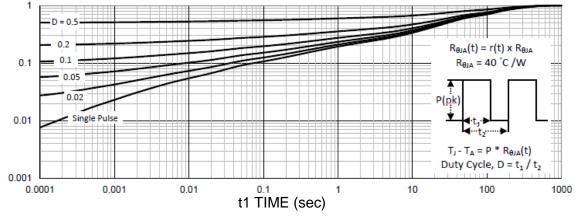
VDS Drain to Source Voltage (V)

9. Safe Operating Area



t1 TIME (SEC)

10. Single Pulse Maximum Power Dissipation

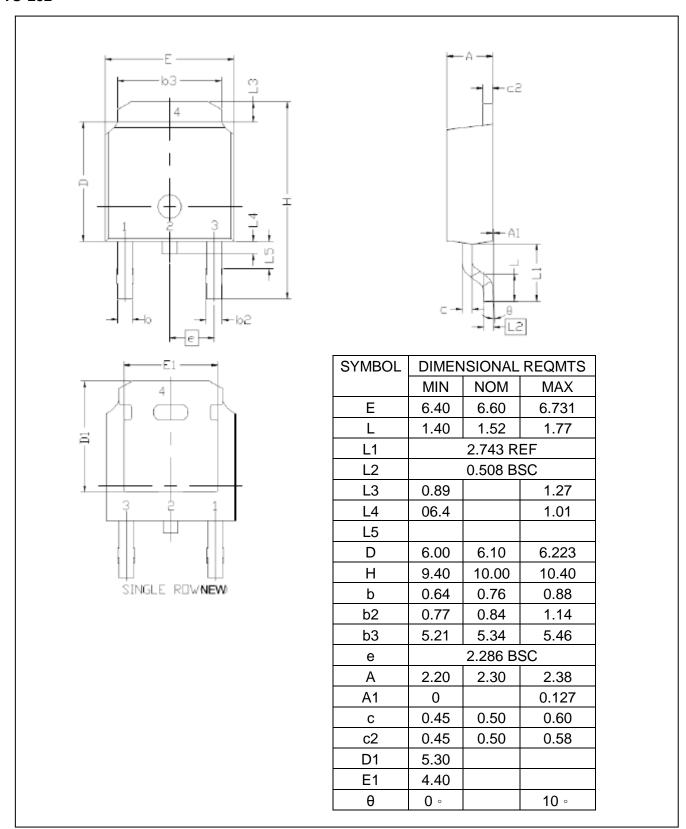


11. Normalized Thermal Transient Junction to Ambient



### **Packing Information**

#### TO-252





#### Notes

ACE does not assume any responsibility for use as critical components in life support devices or systems without the express written approval of the president and general counsel of ACE Electronics Co., LTD. As sued herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and shoes failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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